

DS96F172M/DS96F174C/DS96F174M EIA-485/EIA-422 Quad Differential Drivers

Check for Samples: [DS96F172M](#), [DS96F174C](#), [DS96F174M](#)

FEATURES

- Meets EIA-485 and EIA-422 standards
- Monotonic differential output switching
- TRI-STATE outputs
- Designed for multipoint bus transmission
- Common mode output voltage range: $-7.0V$ to $+12V$
- Operates from single $+5.0V$ supply
- Reduced power consumption
- Thermal shutdown protection
- DS96F172 and DS96F174 are lead and function compatible with the SN75172/174 or the AM26LS31/MC3487
- Military temperature range available
- Qualified for MIL-STD-883C
- Standard military drawings available (SMD)
- Available in DIP (J), LCC (E), and Flatpak (W) packages

DESCRIPTION

The DS96F172 and the DS96F174 are high speed quad differential line drivers designed to meet EIA-485 Standards. The DS96F172 and the DS96F174 offer improved performance due to the use of L-FAST bipolar technology. The use of LFAST technology allows the DS96F172 and DS96F174 to operate at higher speeds while minimizing power consumption.

The DS96F172 and the DS96F174 have TRI-STATE[®] outputs and are optimized for balanced multipoint data bus transmission at rates up to 15 Mbps. The drivers have wide positive and negative common mode range for multipoint applications in noisy environments. Positive and negative current-limiting is provided which protects the drivers from line fault conditions over a $+12V$ to $-7.0V$ common mode range. A thermal shutdown feature is also provided. The DS96F172 features an active high and active low Enable, common to all four drivers. The DS96F174 features separate active high Enables for each driver pair.

Logic Diagram

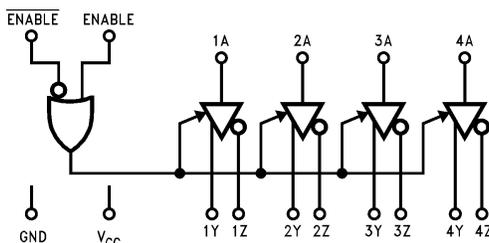


Figure 1. DS96F172

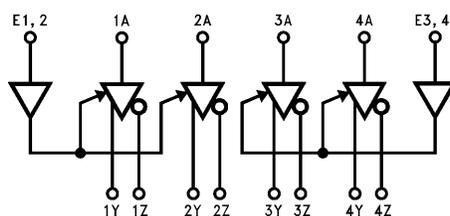


Figure 2. DS96F174



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Function Tables

(Each Driver)

Table 1. DS96F172⁽¹⁾

Input A	Enable		Outputs	
	E	$\bar{\text{E}}$	Y	Z
H	H	X	H	L
L	H	X	L	H
H	X	L	H	L
L	X	L	L	H
X	L	H	Z	Z

Table 2. DS96F174⁽¹⁾

Input A	Enable E	Outputs	
		Y	Z
H	H	H	L
L	H	L	H
X	L	Z	Z

- (1) H = High Level
L = Low Level
X = Don't Care
Z = High Impedance (Off)



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings COMMERCIAL ⁽¹⁾

Specifications for the 883 version of this product are listed separately on the following pages.

Storage Temperature Range (T_{STG})	-65°C to +175°C
Lead Temperature (Soldering, 60 sec.)	300°C
Maximum Package Power Dissipation ⁽²⁾ at 25°C	
Ceramic DIP (J)	1500 mW
Supply Voltage	7.0V
Enable Input Voltage	5.5V

- (1) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The tables of "Electrical Characteristics" provide conditions for actual device operation.
(2) Derate "J" package 10 mW/°C above 25°C.

Recommended Operating Conditions

	Min	Typ	Max	Units
Supply Voltage (V_{CC})				
DS96F174C	4.75	5.0	5.25	V
Common Mode	-7.0		+12.0	V
Output Voltage (V_{OC})				
Output Current HIGH (I_{OH})			-60	mA
Output Current LOW (I_{OL})			60	mA
Operating Temperature (T_A)				
DS96F174C	0		+70	°C

Electrical Characteristics ^{(1) (2)}

Over recommended supply voltage and operating temperature range, unless otherwise specified

Symbol	Parameter	Conditions		Min	Typ	Max	Units
					(3)		
V _{IH}	Input Voltage HIGH			2.0			V
V _{IL}	Input Voltage LOW		T _A = 0°C to +70°C			0.8	V
			T _A = -55°C to +125°C			0.7	
V _{OH}	Output Voltage HIGH	I _{OH} = -33 mA	T _A = 0°C to +70°C	3.0			V
V _{OL}	Output Voltage LOW	I _{OL} = 33 mA	T _A = 0°C to +70°C			2.0	V
V _{IC}	Input Clamp Voltage	I _I = -18 mA				-1.5	V
V _{OD1}	Differential Output Voltage	I _O = 0 mA				6.0	V
V _{OD2}	Differential Output Voltage	R _L = 54Ω, <i>Figure 3</i>	T _A = -55°C	1.2	2.0		V
				1.5			
				2.0		2.3	
V _{OD}	Differential Output Voltage	<i>Figure 4</i>	T _A = 0°C to +70°C	1.0			V
Δ V _{OD}	Change in Magnitude of Differential Output Voltage ⁽⁴⁾	R _L = 54Ω or 100Ω, <i>Figure 3</i>	-40°C to +125°C			±0.2	V
			-55°C to +125°C			±0.4	
V _{OC}	Common Mode Output Voltage ⁽⁵⁾	R _L = 54Ω or 100Ω, <i>Figure 3</i>				3.0	V
Δ V _{OC}	Change in Magnitude of Common Mode Output Voltage ⁽⁴⁾	R _L = 54Ω or 100Ω, <i>Figure 3</i>				±0.2	V
I _O	Output Current with Power Off	V _{CC} = 0V, V _O = -7.0V to +12V				±50	μA
I _{OZ}	High Impedance State Output Current	V _O = -7.0V to +12V			±20	±50	μA
I _{IH}	Input Current HIGH	V _I = 2.4V				20	μA
I _{IL}	Input Current LOW	V _I = 0.4V				-50	μA
I _{OS}	Short Circuit Output Current ⁽⁶⁾		V _O = -7.0V			-250	
			V _O = 0V			-150	mA
			V _O = V _{CC}			150	
			V _O = +12V			250	
I _{CC}	Supply Current (All Drivers)	No Load	Outputs Enabled			50	mA
I _{CCX}			Outputs Disabled			30	

- (1) Unless otherwise specified min/max limits apply across the 0°C to +70°C range for the DS96F174C. All typicals are given for V_{CC} = 5V and T_A = 25°C.
- (2) All currents into the device pins are positive; all currents out of the device pins are negative. All voltages are reference to ground unless otherwise specified.
- (3) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The tables of "Electrical Characteristics" provide conditions for actual device operation.
- (4) Δ|V_{OD}| and Δ|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC} respectively, that occur when the input is changed from a high level to a low level.
- (5) In EIA-422A and EIA-485 standards, V_{OC}, which is the average of the two output voltages with respect to ground, is called output offset voltage, V_{OS}.
- (6) Only one output at a time should be shorted.

COMMERCIAL Switching Characteristics

 $V_{CC} = 5.0V$, $T_A = 25^\circ C$

Symbol	Parameter	Conditions	Min	Typ	Max	Units
t_{DD}	Differential Output Delay Time	$R_L = 60\Omega$, Figure 5		15	20	ns
t_{TD}	Differential Output Transition Time			15	22	ns
t_{PLH}	Propagation Delay Time, Low-to-High Level Output	$R_L = 27\Omega$, Figure 6		12	16	ns
t_{PHL}	Propagation Delay Time, High-to-Low Level Output			12	16	ns
t_{ZH}	Output Enable Time to High Level	$R_L = 110\Omega$, Figure 4		25	32	ns
t_{ZL}	Output Enable Time to Low Level	$R_L = 110\Omega$, Figure 8		25	32	ns
t_{HZ}	Output Disable Time from High Level	$R_L = 110\Omega$, Figure 7		25	30	ns
t_{LZ}	Output Disable Time from Low Level	$R_L = 110\Omega$, Figure 8		20	25	ns
t_{LZL}	Output Disable Time from Low Level with Load Resistor to GND ⁽¹⁾	Figure 8		300		ns
t_{SKEW}	Driver Output to Output	$R_L = 60\Omega$		1.0	4.0	ns

(1) For more information see Application Bulletin, contact Product Marketing.

Absolute Maximum Ratings MIL-STD-883C ⁽¹⁾

For complete Military Specifications, refer to the appropriate SMD or MDS.

Storage Temperature Range (T_{STG})	-65°C to +175°C
Lead Temperature (Soldering, 60 sec.)	300°C
Maximum Package Power Dissipation ⁽²⁾ at 25°C	
Ceramic LCC (E)	2000 mW
Ceramic DIP (J)	1800 mW
Ceramic Flatpak (W)	1000 mW
Supply Voltage	7.0V
Enable Input Voltage	5.5V

- (1) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The tables of "Electrical Characteristics" provide conditions for actual device operation.
- (2) Above $T_A = 25^\circ C$, derate "E" package 13.4, "J" package 12.5, "W" package 7.1 mW/°C

Recommended Operating Conditions

	Min	Typ	Max	Units
Supply Voltage (V_{CC})				
DS96F172M/DS96F174M	4.50	5.0	5.50	V
Common Mode	-7.0		+12.0	V
Output Voltage (V_{OC})				
Output Current HIGH (I_{OH})			-60	mA
Output Current LOW (I_{OL})			60	mA
Operating Temperature (T_A)				
DS96F172M/DS96F174M	-55		+125	°C

Electrical Characteristics ^{(1) (2)}

Over recommended supply voltage and operating temperature range unless otherwise specified

Symbol	Parameter	Conditions		Min	Max	Units
V _{IH}	Input Voltage HIGH			2.0		V
V _{IL}	Input Voltage LOW		T _A = 25°C		0.8	V
			T _A = -55°C, or +125°C		0.7	
V _{IC}	Input Clamp Voltage	I _I = -18 mA			-1.5	V
V _{OD1}	Differential Output Voltage	I _O = 0 mA			6.0	V
V _{OD2}	Differential Output Voltage	R _L = 54Ω, V _{CC} = 4.5V	T _A = -55°C	1.2		
		Figure 3	T _A = 25°C, or +125°C	1.5		V
		R _L = 100Ω, V _{CC} = 4.5V, Figure 3		2.0		
Δ V _{OD}	Change in Magnitude of Differential	R _L = 54Ω or 100Ω,	T _A = 25°C, or +125°C		±0.2	V
	Output Voltage ⁽³⁾	V _{CC} = 4.5V, Figure 3	T _A = -55°C		±0.4	V
V _{OC}	Common Mode Output Voltage ⁽⁴⁾	R _L = 54Ω or 100Ω, Figure 3			3.0	V
Δ V _{OC}	Change in Magnitude of Common	R _L = 54Ω or 100Ω, V _{CC} = 4.5V, Figure 3			±0.2	V
	Mode Output Voltage ⁽³⁾					
I _O	Output Current with Power Off	V _{CC} = 0V, V _O = -7.0V to +12V			±50	μA
I _{OZ}	High Impedance State Output Current	V _O = -7.0V to +12V			±50	μA
I _{IH}	Input Current HIGH	V _I = 2.4V			20	μA
I _{IL}	Input Current LOW	V _I = 0.4V			-50	μA
I _{OS}	Short Circuit Output Current	V _O = -7.0V			-250	mA
	⁽⁵⁾	V _O = 0V			-150	
		V _O = V _{CC}			150	
		V _O = +12V			250	
I _{CC}	Supply Current (All Drivers)	No Load	Outputs Enabled		50	mA
I _{CCX}			Outputs Disabled		30	

- (1) Unless otherwise specified min/max limits apply across the 0°C to +70°C range for the DS96F174C. All typicals are given for V_{CC} = 5V and T_A = 25°C.
- (2) All currents into the device pins are positive; all currents out of the device pins are negative. All voltages are reference to ground unless otherwise specified.
- (3) Δ|V_{OD}| and Δ|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC} respectively, that occur when the input is changed from a high level to a low level.
- (4) In EIA-422A and EIA-485 standards, V_{OC}, which is the average of the two output voltages with respect to ground, is called output offset voltage, V_{OS}.
- (5) Only one output at a time should be shorted.

MIL-STD-883C Switching Characteristics

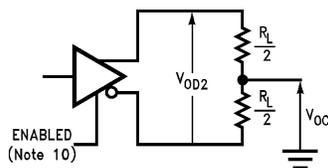
 $V_{CC} = 5.0V$

Symbol	Parameter	Conditions	T _A = 25°C		T _A = 55°C	T _A = 125°C	Units
			Typ	Max	Max	Max	
t _{DD}	Differential Output Delay Time	R _L = 60Ω, C _L = 15 pF,	15	22	30	30	ns
t _{TD}	Differential Output Transition Time	Figure 5	15	22	40	40	ns
t _{PLH}	Propagation Delay Time, Low-to-High Level Output	R _L = 27Ω, C _L = 15 pF, Figure 6	12	16	25	25	ns
t _{PHL}	Propagation Delay Time, High-to-Low Level Output		12	16	25	25	ns
t _{ZH}	Output Enable Time to High Level	R _L = 110Ω, Figure 7	25	32	40	40	ns
t _{ZL}	Output Enable Time to Low Level	R _L = 110Ω, Figure 8	25	35	100	100	ns
t _{HZ}	Output Disable Time from High Level	R _L = 110Ω, Figure 7 , (1)	25	30	80	80	ns
t _{LZ}	Output Disable Time from Low Level	R _L = 110Ω, Figure 8	20	25	40	40	ns
t _{LZL}	Output Disable Time from Low Level with Load Resistor to GND ⁽²⁾	Figure 8	300				ns
t _{SKEW}	Driver Output to Output	R _L = 60Ω	1.0	4.0	10	10	ns

(1) Not tested for DS96F172MW-MIL device.

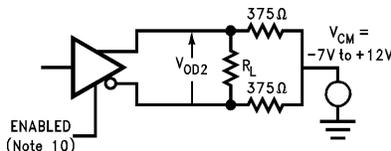
(2) For more information see Application Bulletin, Contact Product Marketing.

Parameter Measurement Information



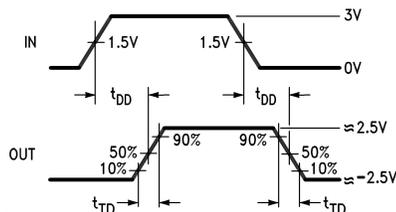
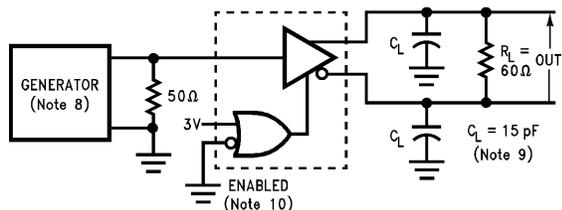
(10) DS96F172 with active high and active low Enables is shown. DS96F174 has active high Enable only.

Figure 3. Differential and Common Mode Output Voltage



(10) DS96F172 with active high and active low Enables is shown. DS96F174 has active high Enable only.

Figure 4. Differential Output Voltage with Varying Common Mode Voltage



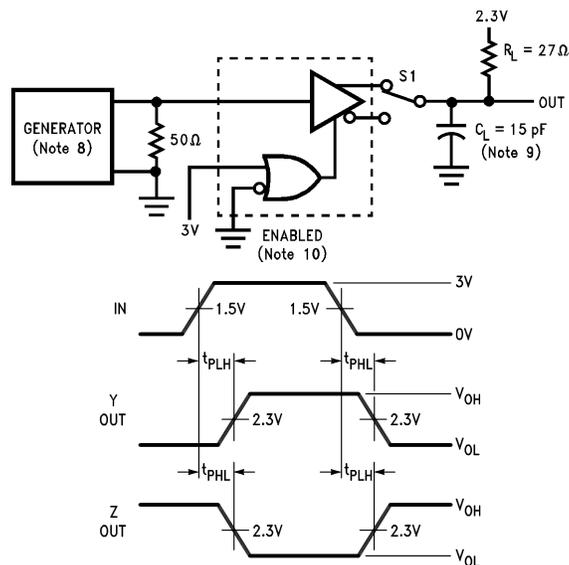
(8) The input pulse is supplied by a generator having the following characteristics: $f = 1.0 \text{ MHz}$, duty cycle = 50%, $t_r \leq 5.0 \text{ ns}$, $t_f \leq 5.0 \text{ ns}$, $Z_O = 50\Omega$.

(9) C_L includes probe and jig capacitance

(10) DS96F172 with active high and active low Enables is shown. DS96F174 has active high Enable only.

Figure 5. Differential Output Delay and Transition Times

Parameter Measurement Information (continued)

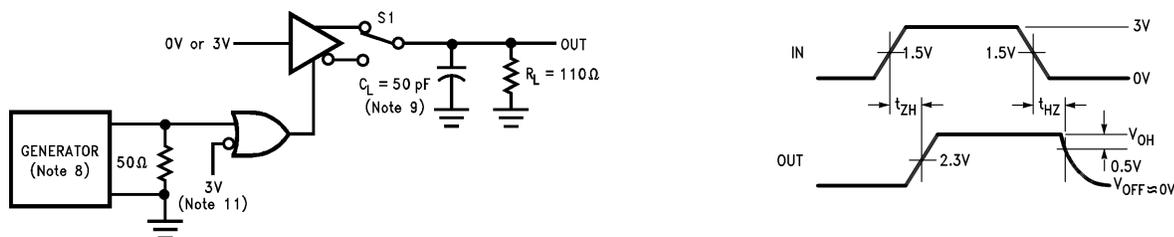


(8) The input pulse is supplied by a generator having the following characteristics: $f = 1.0$ MHz, duty cycle = 50%, $t_r \leq 5.0$ ns, $t_f \leq 5.0$ ns, $Z_O = 50\Omega$.

(9) C_L includes probe and jig capacitance

(10) DS96F172 with active high and active low Enables is shown. DS96F174 has active high Enable only.

Figure 6. Propagation Delay Times



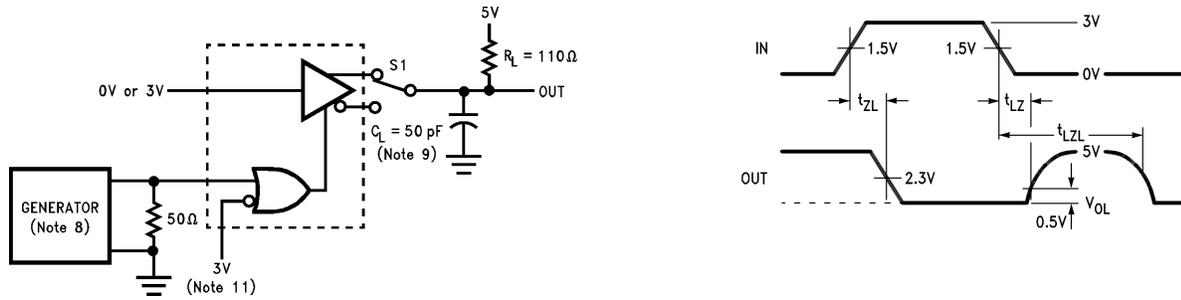
(8) The input pulse is supplied by a generator having the following characteristics: $f = 1.0$ MHz, duty cycle = 50%, $t_r \leq 5.0$ ns, $t_f \leq 5.0$ ns, $Z_O = 50\Omega$.

(9) C_L includes probe and jig capacitance

(11) To test the active low Enable \bar{E} of DS96F172 ground E and apply an inverted waveform to \bar{E} . DS96F174 has active high Enable only.

Figure 7. t_{ZH} and t_{HZ}

Parameter Measurement Information (continued)



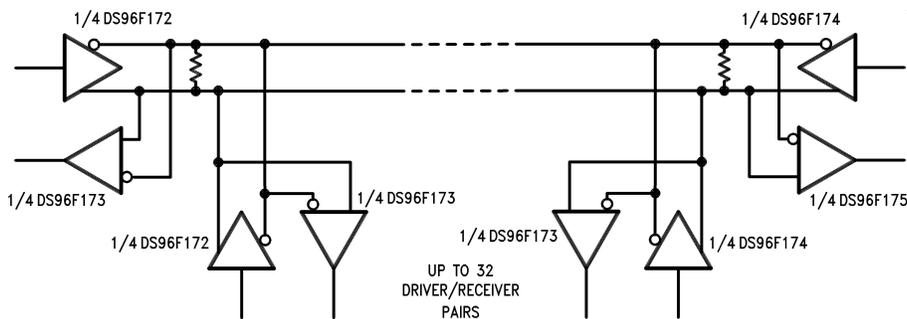
(8) The input pulse is supplied by a generator having the following characteristics: $f = 1.0 \text{ MHz}$, duty cycle = 50%, $t_r \leq 5.0 \text{ ns}$, $t_f \leq 5.0 \text{ ns}$, $Z_O = 50\Omega$.

(9) C_L includes probe and jig capacitance

(11) To test the active low Enable \bar{E} of DS96F172 ground E and apply an inverted waveform to \bar{E} . DS96F174 has active high Enable only.

Figure 8. t_{ZL} , t_{LZ} , t_{LZL}

TYPICAL APPLICATION



The line length should be terminated at both ends in its characteristic impedance. Stub lengths off the main line should be kept as short as possible.

Connection Diagrams

16-Lead Ceramic Dual-In-Line Package

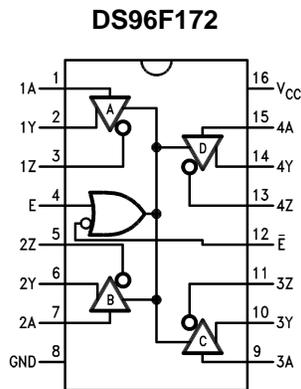


Figure 9. Top View

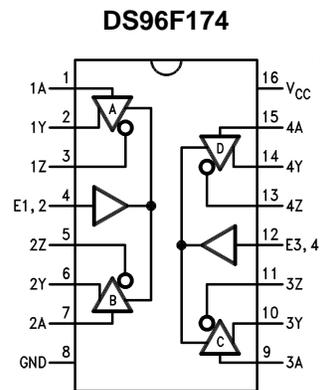
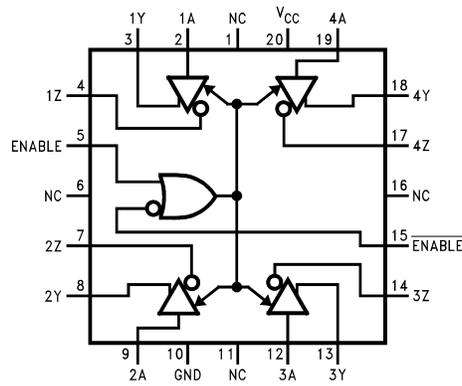


Figure 10. Top View

20-Lead Ceramic Leadless Chip Carrier



NC = No connection

Figure 11. Top View

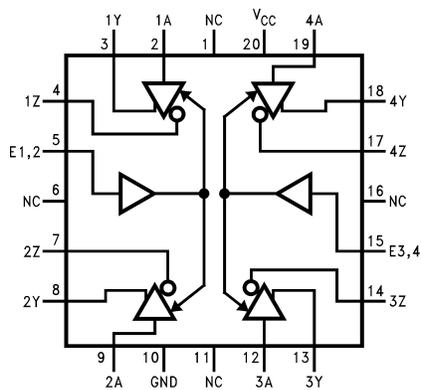
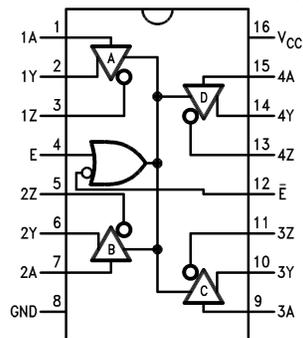
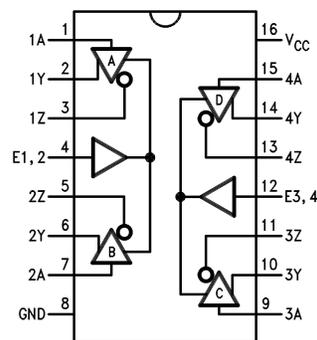


Figure 12. Top View

16-Lead Ceramic Flatpack**Figure 13. Top View****Figure 14. Top View**

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